

WHAT IS CLAIMED IS:

1. A method of fabricating electronic parts comprising the steps of:

5 (a) mounting electronic elements in regular cavities that are two-dimensionally arranged on a baseboard on which dummy cavities are provided so as to surround the regular cavities; and

10 (b) covering a top of the baseboard with a resin sheet.

2. The method as claimed in claim 1, wherein the step (b) includes a step of supplying resin of the resin sheet to given dummy cavities having bottoms that
15 are not metallized.

3. The method as claimed in claim 1, wherein the step (b) includes a step of placing the resin sheet on the top of the baseboard so as to cover the regular
20 and dummy cavities and pressurizing the resin sheet while heating, so that the regular and dummy cavities can be hermetically sealed.

4. The method as claimed in claim 1, further
25 comprising a step (c) of dividing the baseboard into separate electronic parts each of which includes one of the electronic elements in a corresponding one of the regular cavities.

30 5. The method as claimed in claim 1, wherein the dummy cavities are at least 150 μm away from regular cavities located at outermost positions.

35 6. The method as claimed in claim 1, wherein the dummy cavities are away from regular cavities located at outermost positions at a distance equal to that at which the regular cavities are two-

dimensionally arranged.

7. The method as claimed in claim 1, wherein
the dummy cavities are away from regular cavities
5 located at outermost positions at a distance equal to
or longer than a gap between sidewalls of the regular
cavities and the electronic elements in the regular
cavities.

10 8. The method as claimed in claim 1, wherein
the dummy cavities are arranged in rows and columns of
a two-dimensional arrangement of the regular cavities.

9. The method as claimed in claim 1, wherein
15 each of the dummy cavities, is arranged common to at
least two rows and columns of a two-dimensional
arrangement of the regular cavities.

10 10. The method as claimed in claim 1, wherein
the dummy cavities make a single groove that totally
surrounds a two-dimensional arrangement of the regular
cavities.

11. The method as claimed in claim 1, wherein
25 the dummy cavities are at least 50 μm deep.

12. The method as claimed in claim 1, further
comprising a step of attaching a wiring board to a
backside of the baseboard so that terminals on the
30 wiring boards are electrically connected to terminals
in the regular cavities by via interconnections
provided in the baseboard.

13. The method as claimed in claim 1, wherein
35 the electronic elements are surface acoustic wave
filter chips, and the electronic parts are surface
acoustic wave devices.

14. A baseboard used for electronic parts sealed with resin comprising:

5 regular cavities that can house electronic elements and are two-dimensionally arranged; and
dummy cavities arranged so as to surround the regular cavities.

10 15. The baseboard as claimed in claim 14, wherein no metallization is provided to bottoms of the dummy cavities.

15 16. The baseboard as claimed in claim 14, wherein the dummy cavities are at least 150 μm away from regular cavities located at outermost positions.

20 17. The baseboard as claimed in claim 14, wherein the dummy cavities are away from regular cavities located at outermost positions at a distance equal to that at which the regular cavities are two-dimensionally arranged.

25 18. The baseboard as claimed in claim 14, wherein the dummy cavities are away from regular cavities located at outermost positions at a distance equal to or longer than a gap between sidewalls of the regular cavities and the electronic elements in the regular cavities.

30 19. The baseboard as claimed in claim 14, wherein the dummy cavities are arranged in rows and columns of a two-dimensional arrangement of the regular cavities.

35 20. The baseboard as claimed in claim 14, wherein each of the dummy cavities is arranged common to at least two rows and columns of a two-dimensional

arrangement of the regular cavities.

21. The baseboard as claimed in claim 14,
wherein the dummy cavities make a single groove that
5 totally surrounds a two-dimensional arrangement of the
regular cavities.

22. The baseboard as claimed in claim 14,
wherein the dummy cavities are at least 50 μm deep.
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23. The baseboard as claimed in claim 14,
wherein the baseboard has a backside to which a wiring
board is attached so that terminals on the wiring
boards are electrically connected to terminals in the
15 regular cavities by via interconnections provided in
the baseboard.

24. The baseboard as claimed in claim 14,
wherein the electronic elements are surface acoustic
20 wave filter chips, and the electronic parts are surface
acoustic wave devices.